100 mA, Low Power Low **Dropout Voltage Regulator**

The LP2950 and LP2951 are micropower voltage regulators that are specifically designed to maintain proper regulation with an extremely low input-to-output voltage differential. These devices feature a very low quiescent bias current of 75 µA and are capable of supplying output currents in excess of 100 mA. Internal current and thermal limiting protection is provided.

The LP2951 has three additional features. The first is the $\overline{\text{Error}}$ Output that can be used to signal external circuitry of an out of regulation condition, or as a microprocessor power-on reset. The second feature allows the output voltage to be preset to 5.0 V, 3.3 V or 3.0 V output (depending on the version) or programmed from 1.25 V to 29 V. It consists of a pinned out resistor divider along with direct access to the Error Amplifier feedback input. The third feature is a Shutdown input that allows a logic level signal to turn-off or turn-on the regulator output.

Due to the low input-to-output voltage differential and bias current specifications, these devices are ideally suited for battery powered computer, consumer, and industrial equipment where an extension of useful battery life is desirable. The LP2950 is available in the three pin case 29 and DPAK packages, and the LP2951 is available in the eight pin dual-in-line, SOIC-8 and Micro8 surface mount packages. The 'A' suffix devices feature an initial output voltage tolerance $\pm 0.5\%$.

Features

- Low Quiescent Bias Current of 75 μA
- Low Input-to-Output Voltage Differential of 50 mV at 100 µA and 380 mV at 100 mA
- 5.0 V, 3.3 V or 3.0 V $\pm 0.5\%$ Allows Use as a Regulator or Reference
- Extremely Tight Line and Load Regulation
- Requires Only a 1.0 μF Output Capacitor for Stability
- Internal Current and Thermal Limiting
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and RoHS Compliant

LP2951 Additional Features

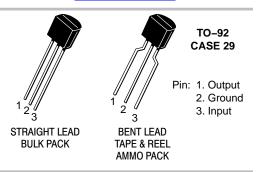
- Error Output Signals an Out of Regulation Condition
- Output Programmable from 1.25 V to 29 V
- Logic Level Shutdown Input

(See Following Page for Device Information.)



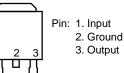
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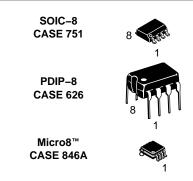




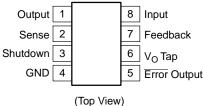


PIN CONNECTIONS

(Top View) Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.



PIN CONNECTIONS



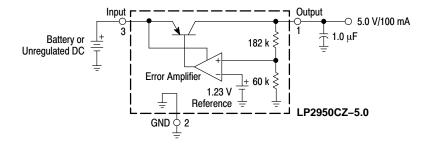
ORDERING & MARKING INFORMATION

See detailed ordering and shipping information in the package dimensions section on pages 14 and 15 of this data sheet. See general marking information in the device marking section on page 17 of this data sheet.

DEVICE INFORMATION

			Operating Ambient		
Package	3.0 V	3.3 V	5.0 V	Adjustable	Temperature Range
TO-92	LP2950CZ-3.0	LP2950CZ-3.3	LP2950CZ-5.0	Not	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
Suffix Z	LP2950ACZ-3.0	LP2950ACZ-3.3	LP2950ACZ-5.0	Available	
DPAK	LP2950CDT-3.0	LP2950CDT-3.3	LP2950CDT-5.0	Not	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
Suffix DT	LP2950ACDT-3.0	LP2950ACDT-3.3	LP2950ACDT-5.0	Available	
SOIC-8	-	NCV2951ACD-3.3R2	NCV2951ACDR2	NCV2951CDR2	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
SOIC-8	LP2951CD-3.0	LP2951CD-3.3	LP2951CD	LP2951CD	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
Suffix D	LP2951ACD-3.0	LP2951ACD-3.3	LP2951ACD	LP2951ACD	
Micro8	LP2951CDM-3.0	LP2951CDM-3.3	LP2951CDM	LP2951CDM	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
Suffix DM	LP2951ACDM-3.0	LP2951ACDM-3.3	LP2951ACDM	LP2951ACDM	
DIP-8	LP2951CN-3.0	LP2951CN-3.3	LP2951CN	LP2951CN	$T_A = -40^{\circ} \text{ to } +125^{\circ}\text{C}$
Suffix N	LP2951ACN-3.0	LP2951ACN-3.3	LP2951ACN	LP2951ACN	

LP2950Cx-xx / LP2951Cxx-xx LP2950ACx-xx / LP2951ACxx-xx 1% Output Voltage Precision at T_A = 25°C 0.5% Output Voltage Precision at T_A = 25°C



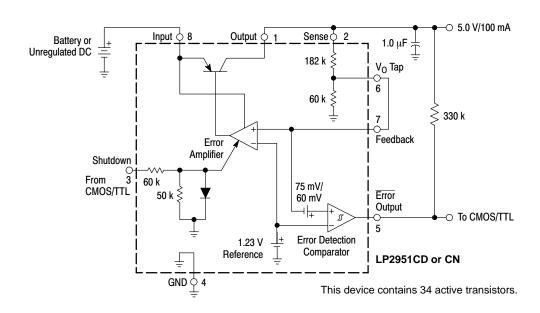


Figure 1. Representative Block Diagrams

MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted.)

Rating	Symbol	Value	Unit
Input Voltage	V _{CC}	30	Vdc
Peak Transient Input Voltage (t < 300 ms)	V _{CC}	32	Vdc
Power Dissipation and Thermal Characteristics			
Maximum Power Dissipation	P _D	Internally Limited	W
Case 751(SOIC-8) D Suffix			
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	180	°C/W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	45	°C/W
Case 369A (DPAK) DT Suffix (Note 1)			
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	92	°C/W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	6.0	°C/W
Case 29 (TO-226AA/TO-92) Z Suffix			
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	160	°C/W
Thermal Resistance, Junction-to-Case	$R_{ hetaJC}$	83	°C/W
Case 626 N Suffix			
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	105	°C/W
Case 846A (Micro8) DM Suffix			
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	240	°C/W
Feedback Input Voltage	V_{fb}	-1.5 to +30	Vdc
Shutdown Input Voltage	V _{sd}	-0.3 to +30	Vdc
Error Comparator Output Voltage	V _{err}	-0.3 to +30	Vdc
Operating Ambient Temperature Range	T _A	-40 to +125	°C
Maximum Die Junction Temperature Range	TJ	+150	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS

 $(V_{in} = V_O + 1.0 \text{ V}, I_O = 100 \mu\text{A}, C_O = 1.0 \mu\text{F}, T_A = 25^{\circ}\text{C}$ [Note 3], unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
Output Voltage, 5.0 V Versions	Vo				V
$V_{in} = 6.0 \text{ V}, I_O = 100 \mu\text{A}, T_A = 25^{\circ}\text{C}$					
LP2950C-5.0/LP2951C/NCV2951C*		4.950	5.000	5.050	
LP2950AC-5.0/LP2951AC/NCV2951AC*		4.975	5.000	5.025	
$T_A = -40 \text{ to } +125^{\circ}\text{C}$					
LP2950C-5.0/LP2951C/NCV2951C*		4.900	_	5.100	
LP2950AC-5.0/LP2951AC/NCV2951AC*		4.940	_	5.060	
V_{in} = 6.0 to 30 V, I_{O} = 100 μA to 100 mA, T_{A} = -40 to +125 °C					
LP2950C-5.0/LP2951C/NCV2951C*		4.880	_	5.120	
LP2950AC-5.0/LP2951AC/NCV2951AC*		4.925	-	5.075	
Output Voltage, 3.3 V Versions	Vo				V
$V_{in} = 4.3 \text{ V}, I_O = 100 \mu\text{A}, T_A = 25^{\circ}\text{C}$					
LP2950C-3.3/LP2951C-3.3		3.267	3.300	3.333	
LP2950AC-3.3/LP2951AC-3.3/NCV2951AC-3.3*		3.284	3.300	3.317	
$T_A = -40 \text{ to } +125^{\circ}\text{C}$					
LP2950C-3.3/LP2951C-3.3		3.234	-	3.366	
LP2950AC-3.3/LP2951AC-3.3/NCV2951AC-3.3*		3.260	-	3.340	
V_{in} = 4.3 to 30 V, I_O = 100 μA to 100 mA, T_A = -40 to +125°C					
LP2950C-3.3/LP2951C-3.3		3.221	-	3.379	
LP2950AC-3.3/LP2951AC-3.3/NCV2951AC-3.3*		3.254	-	3.346	
Output Voltage, 3.0 V Versions	Vo				V
$V_{in} = 4.0 \text{ V}, I_{O} = 100 \mu\text{A}, T_{A} = 25^{\circ}\text{C}$					
LP2950C-3.0/LP2951C-3.0		2.970	3.000	3.030	
LP2950AC-3.0/LP2951AC-3.0		2.985	3.000	3.015	
$T_A = -40 \text{ to } +125^{\circ}\text{C}$					
LP2950C-3.0/LP2951C-3.0		2.940	-	3.060	
LP2950AC-3.0/LP2951AC-3.0		2.964	_	3.036	
V_{in} = 4.0 to 30 V, I_O = 100 μA to 100 mA, T_A = -40 to +125°C					
LP2950C-3.0/LP2951C-3.0		2.928	_	3.072	
LP2950AC-3.0/LP2951AC-3.0		2.958	_	3.042	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. The Junction-to-Ambient Thermal Resistance is determined by PCB copper area per Figure 29.
- This device series contains ESD protection and exceeds the following tests:

Human Body Model (HBM), 2000 V, Class 2, JESD22 A114–C Machine Model (MM), 200 V, Class B, JESD22 A115–A Charged Device Model (CDM), 2000 V, Class IV, JESD22 C101–C

- 3. Low duty pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
- 4. V_{O(nom)} is the part number voltage option.
- 5. Noise tests on the LP2951 are made with a 0.01 μ F capacitor connected across Pins 7 and 1.

*NCV prefix is for automotive and other applications requiring site and change control.

ELECTRICAL CHARACTERISTICS (continued)

(V_{in} = V_O + 1.0 V, I_O = 100 μ A, C_O = 1.0 μ F, T_A = 25°C [Note 8], unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
Line Regulation (V _{in} = V _{O(nom)} +1.0 V to 30 V) (Note 9)	Reg _{line}				%
LP2950C-XX/LP2951C/LP2951C-XX/NCV2951C*		-	0.08	0.20	
LP2950AC-XX/LP2951AC/LP2951AC-XX/NCV2951AC*		-	0.04	0.10	
Load Regulation ($I_O = 100 \mu A$ to 100 mA)	Reg _{load}				%
LP2950C-XX/LP2951C/LP2951C-XX/NCV2951C*		_	0.13	0.20	
LP2950AC-XX/LP2951AC/LP2951AC-XX/NCV2951AC*		-	0.05	0.10	
Dropout Voltage	$V_I - V_O$				mV
$I_O = 100 \mu A$		_	30	80	
$I_{O} = 100 \text{ mA}$		_	350	450	
Supply Bias Current	I _{CC}				
$I_{O} = 100 \mu\text{A}$		_	93	120	μΑ
I _O = 100 mA		_	4.0	12	mA
Dropout Supply Bias Current (V_{in} = $V_{O(nom)}$ – 0.5 V, I_O = 100 μ A) (Note 9)	I _{CCdropout}	_	110	170	μΑ
Current Limit (V _O Shorted to Ground)	I _{Limit}	_	220	300	mA
Thermal Regulation	Reg _{thermal}	_	0.05	0.20	%/W
Output Noise Voltage (10 Hz to 100 kHz) (Note 10)	V _n				μVrms
$C_L = 1.0 \mu\text{F}$		-	126	_	
$C_L = 100 \mu\text{F}$		_	56	_	
LP2951A/LP2951AC Only					
Reference Voltage (T _A = 25°C)	V _{ref}				V
LP2951C/LP2951C-XX/NCV2951C*		1.210	1.235	1.260	
LP2951AC/LP2951AC-XX/NCV2951AC*		1.220	1.235	1.250	
Reference Voltage ($T_A = -40 \text{ to } +125^{\circ}\text{C}$)	V_{ref}				V
LP2951C/LP2951C-XX/NCV2951C*		1.200	_	1.270	
LP2951AC/LP2951AC-XX/NCV2951AC*		1.200	_	1.260	
Reference Voltage ($T_A = -40 \text{ to } +125^{\circ}\text{C}$)	V_{ref}				V
$I_0 = 100 \mu A$ to 100 mA, $V_{in} = 23$ to 30 V					
LP2951C/LP2951C-XX/NCV2951C*		1.185	-	1.285	
LP2951AC/LP2951AC-XX/NCV2951AC*		1.190	_	1.270	
Feedback Pin Bias Current	I _{FB}	_	15	40	nA
Error Comparator		, ,		•	
Output Leakage Current (V _{OH} = 30 V)	I _{lkg}	-	0.01	1.0	μΑ
Output Low Voltage ($V_{in} = 4.5 \text{ V}$, $I_{OL} = 400 \mu\text{A}$)	V_{OL}	-	150	250	mV
Upper Threshold Voltage (V _{in} = 6.0 V)	V_{thu}	40	45	-	mV
Lower Threshold Voltage (V _{in} = 6.0 V)	V_{thl}	-	60	95	mV
Hysteresis (V _{in} = 6.0 V)	V_{hy}	_	15	_	mV
Shutdown Input					
Input Logic Voltage	V _{shtdn}				V
Logic "0" (Regulator "On")		0	_	0.7	
Logic "1" (Regulator "Off")		2.0		30	
Shutdown Pin Input Current	I _{shtdn}				μΑ
$V_{shtdn} = 2.4 V$		_	35	50	
$V_{shtdn} = 30 \text{ V}$			450	600	
Regulator Output Current in Shutdown Mode	l _{off}	_	3.0	10	μΑ
$(V_{in} = 30 \text{ V}, V_{shtdn} = 2.0 \text{ V}, V_{O} = 0, \text{Pin 6 Connected to Pin 7})$	1				

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. The Junction–to–Ambient Thermal Resistance is determined by PCB copper area per Figure 29.

^{7.} ESD data available upon request.

^{8.} Low duty pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

^{9.} $V_{O(nom)}$ is the part number voltage option. 10. Noise tests on the LP2951 are made with a 0.01 μF capacitor connected across Pins 7 and 1.

^{*}NCV prefix is for automotive and other applications requiring site and change control.

DEFINITIONS

Dropout Voltage – The input/output voltage differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 100 mV below its nominal value (which is measured at 1.0 V differential), dropout voltage is affected by junction temperature, load current and minimum input supply requirements.

Line Regulation – The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that average chip temperature is not significantly affected.

Load Regulation – The change in output voltage for a change in load current at constant chip temperature.

Maximum Power Dissipation – The maximum total device dissipation for which the regulator will operate within specifications.

Bias Current – Current which is used to operate the regulator chip and is not delivered to the load.

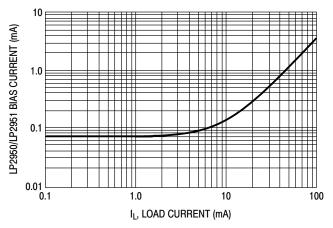


Figure 2. Quiescent Current

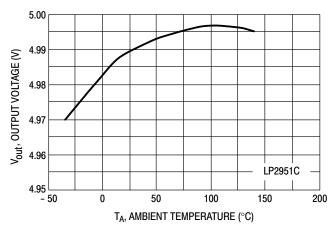


Figure 4. Output Voltage versus Temperature

Output Noise Voltage – The RMS ac voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

Leakage Current – Current drawn through a bipolar transistor collector–base junction, under a specified collector voltage, when the transistor is "off".

Upper Threshold Voltage – Voltage applied to the comparator input terminal, below the reference voltage which is applied to the other comparator input terminal, which causes the comparator output to change state from a logic "0" to "1".

Lower Threshold Voltage – Voltage applied to the comparator input terminal, below the reference voltage which is applied to the other comparator input terminal, which causes the comparator output to change state from a logic "1" to "0".

Hysteresis – The difference between Lower Threshold voltage and Upper Threshold voltage.

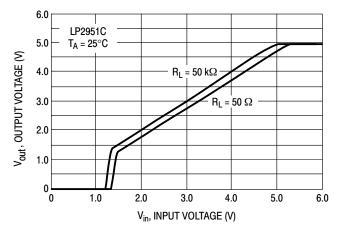


Figure 3. 5.0 V Dropout Characteristics over Load

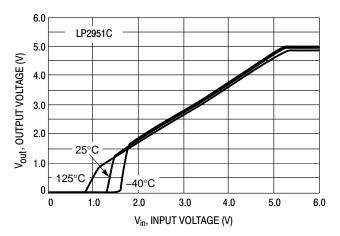


Figure 5. 5.0 V Dropout Characteristics with $$R_L$ = 50~\Omega$

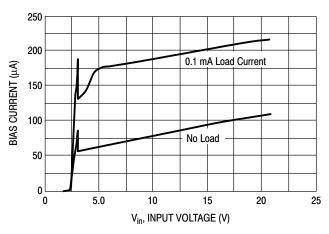


Figure 6. Input Current

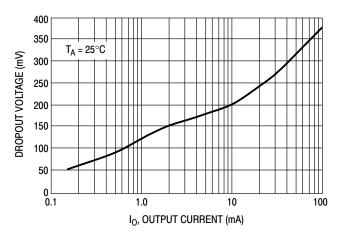


Figure 7. Dropout Voltage versus Output Current

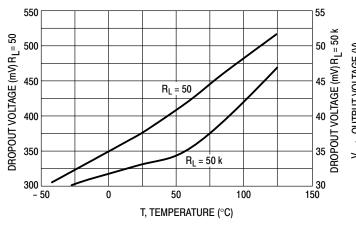


Figure 8. Dropout Voltage versus Temperature

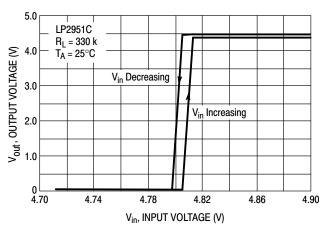


Figure 9. Error Comparator Output

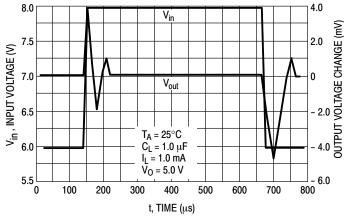


Figure 10. Line Transient Response

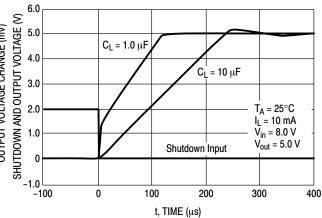


Figure 11. LP2951 Enable Transient

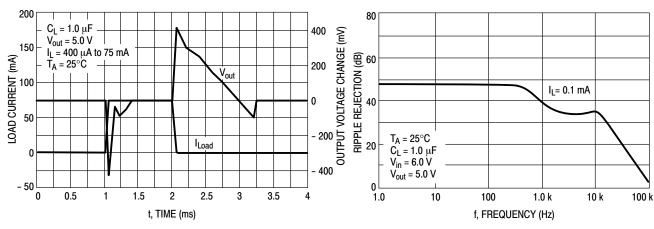


Figure 12. Load Transient Response

Figure 13. Ripple Rejection

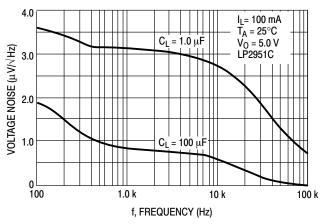


Figure 14. Output Noise

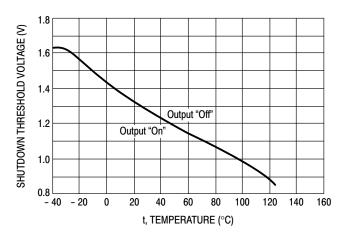


Figure 15. Shutdown Threshold Voltage versus Temperature

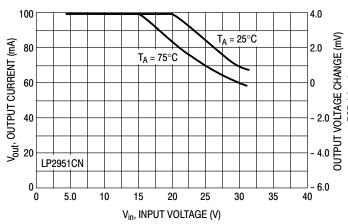


Figure 16. Maximum Rated Output Current

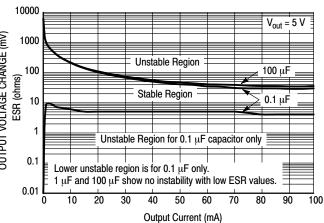


Figure 17. Output Stability versus Output Capacitor Change

APPLICATIONS INFORMATION

Introduction

The LP2950/LP2951 regulators are designed with internal current limiting and thermal shutdown making them user–friendly. Typical application circuits for the LP2950 and LP2951 are shown in Figures 20 through 28.

These regulators are not internally compensated and thus require a 1.0 μF (or greater) capacitance between the LP2950/LP2951 output terminal and ground for stability. Most types of aluminum, tantalum or multilayer ceramic will perform adequately. Solid tantalums or appropriate multilayer ceramic capacitors are recommended for operation below $25^{\circ}C.$

At lower values of output current, less output capacitance is required for output stability. The capacitor can be reduced to 0.33 μF for currents less than 10 mA, or 0.1 μF for currents below 1.0 mA. Using the 8 pin versions at voltages less than 5.0 V operates the error amplifier at lower values of gain, so that more output capacitance is needed for stability. For the worst case operating condition of a 100 mA load at 1.23 V output (output Pin 1 connected to the feedback Pin 7) a minimum capacitance of 3.3 μF is recommended.

The LP2950 will remain stable and in regulation when operated with no output load. When setting the output voltage of the LP2951 with external resistors, the resistance values should be chosen to draw a minimum of $1.0~\mu A$.

A bypass capacitor is recommended across the LP2950/LP2951 input to ground if more than 4 inches of wire connects the input to either a battery or power supply filter capacitor.

Input capacitance at the LP2951 Feedback Pin 7 can create a pole, causing instability if high value external resistors are used to set the output voltage. Adding a 100 pF capacitor between the Output Pin 1 and the Feedback Pin 7 and increasing the output filter capacitor to at least 3.3 μF will stabilize the feedback loop.

Error Detection Comparator

The comparator switches to a positive logic low whenever the LP2951 output voltage falls more than approximately 5.0% out of regulation. This value is the comparator's designed—in offset voltage of 60 mV divided by the 1.235 V internal reference. As shown in the representative block diagram. This trip level remains 5.0% below normal regardless of the value of regulated output voltage. For example, the error flag trip level is 4.75 V for a normal 5.0 V regulated output, or 9.50 V for a 10 V output voltage.

Figure 2 is a timing diagram which shows the $\overline{\text{ERROR}}$ signal and the regulated output voltage as the input voltage

to the LP2951 is ramped up and down. The $\overline{\text{ERROR}}$ signal becomes valid (low) at about 1.3 V input. It goes high when the input reaches about 5.0 V (Vout exceeds about 4.75 V). Since the LP2951's dropout voltage is dependent upon the load current (refer to the curve in the Typical Performance Characteristics), the input voltage trip point will vary with load current. The output voltage trip point does not vary with load.

The error comparator output is an open collector which requires an external pullup resistor. This resistor may be returned to the output or some other voltage within the system. The resistance value should be chosen to be consistent with the 400 μA sink capability of the error comparator. A value between 100 k Ω and 1.0 M Ω is suggested. No pullup resistance is required if this output is unused.

When operated in the power down mode ($V_{in}=0\ V$), the error comparator output will go high if it has been pulled up to an external supply (the output transistor is in high impedance state). To avoid this invalid response, the error comparator output should be pulled up to V_{out} (see Figure 18).

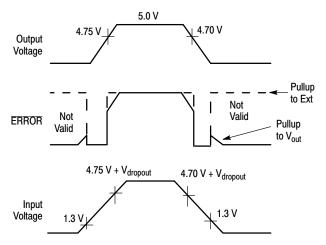


Figure 18. ERROR Output Timing

Programming the Output Voltage (LP2951)

The LP2951CX may be pin-strapped for the nominal fixed output voltage using its internal voltage divider by tying Pin 1 (output) to Pin 2 (sense) and Pin 7 (feedback) to Pin 6 (5.0 V tap). Alternatively, it may be programmed for any output voltage between its 1.235 reference voltage and its 30 V maximum rating. An external pair of resistors is required, as shown in Figure 19.

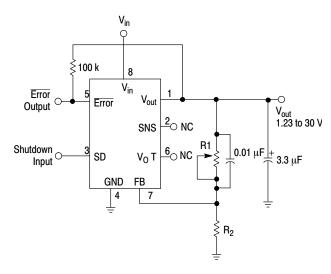


Figure 19. Adjustable Regulator

The complete equation for the output voltage is:

$$V_{out} = V_{ref} (1 + R1/R2) + I_{FB} R1$$

where V_{ref} is the nominal 1.235 V reference voltage and I_{FB} is the feedback pin bias current, nominally -20 nA. The minimum recommended load current of 1.0 μ A forces an upper limit of 1.2 M Ω on the value of R2, if the regulator must work with no load. I_{FB} will produce a 2% typical error in V_{out} which may be eliminated at room temperature by adjusting R1. For better accuracy, choosing R2 = 100 k reduces this error to 0.17% while increasing the resistor program current to 12 μ A. Since the LP2951 typically draws 75 μ A at no load with Pin 2 open circuited, the extra 12 μ A of current drawn is often a worthwhile tradeoff for eliminating the need to set output voltage in test.

Output Noise

In many applications it is desirable to reduce the noise present at the output. Reducing the regulator bandwidth by increasing the size of the output capacitor is the only method for reducing noise on the 3 lead LP2950. However, increasing the capacitor from 1.0 μF to 220 μF only decreases the noise from 430 μV to 160 μV rms for a 100 kHz bandwidth at the 5.0 V output.

Noise can be reduced fourfold by a bypass capacitor across R1, since it reduces the high frequency gain from 4 to unity. Pick

$$C_{\text{Bypass}} \approx \frac{1}{2\pi R1 \times 200 \text{ Hz}}$$

or about 0.01 μ F. When doing this, the output capacitor must be increased to 3.3 μ F to maintain stability. These changes reduce the output noise from 430 μ V to 126 μ Vrms for a 100 kHz bandwidth at 5.0 V output. With bypass capacitor added, noise no longer scales with output voltage so that improvements are more dramatic at higher output voltages.

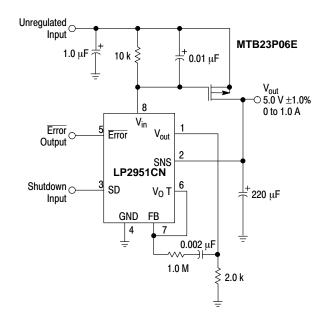


Figure 20. 1.0 A Regulator with 1.2 V Dropout

TYPICAL APPLICATIONS

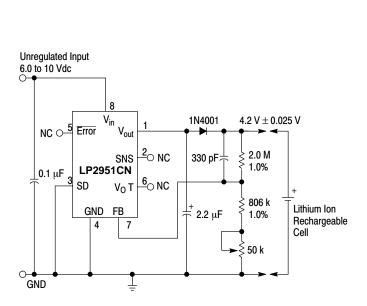


Figure 21. Lithium Ion Battery Cell Charger

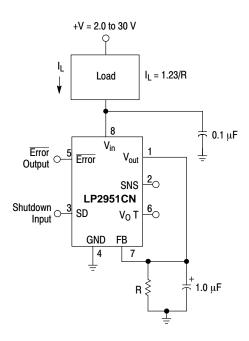


Figure 22. Low Drift Current Sink

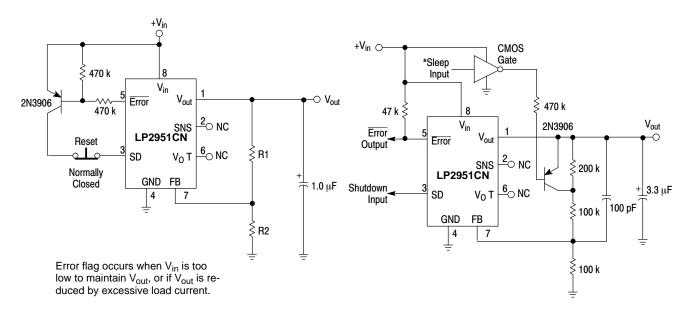
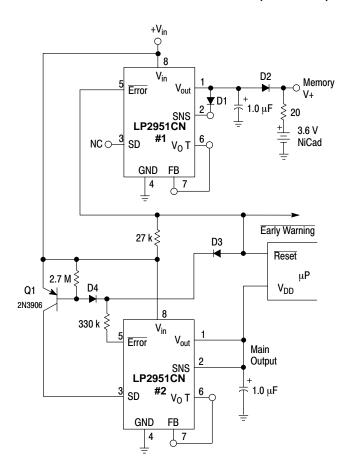


Figure 23. Latch Off When Error Flag Occurs

Figure 24. 5.0 V Regulator with 2.5 V Sleep Function



All diodes are 1N4148.

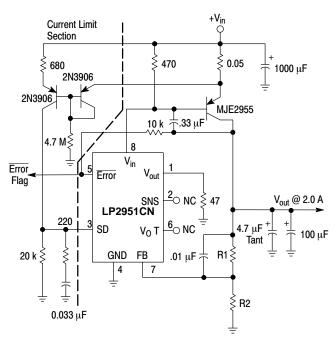
Early Warning flag on low input voltage.

Main output latches off at lower input voltages.

Battery backup on auxiliary output.

Operation: Regulator #1's V_{out} is programmed one diode drop above 5.0 V. Its error flag becomes active when $V_{in} \leq 5.7$ V. When V_{in} drops below 5.3 V, the error flag of regulator #2 becomes active and via Q1 latches the main output "off". When V_{in} again exceeds 5.7 V, regulator #1 is back in regulation and the early warning signal rises, unlatching regulator #2 via D3.

Figure 25. Regulator with Early Warning and Auxiliary Output



 $V_{out} = 1.25V (1.0 + R1/R2)$

For 5.0 V output, use internal resistors. Wire Pin 6 to 7, and wire Pin 2 to +V $_{\rm out}$ Bus.

Figure 26. 2.0 A Low Dropout Regulator

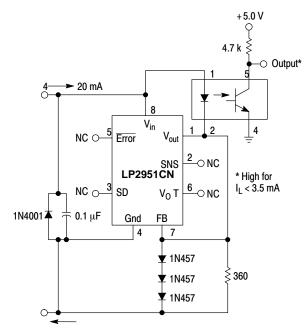


Figure 27. Open Circuit Detector for 4.0 to 20 mA Current Loop

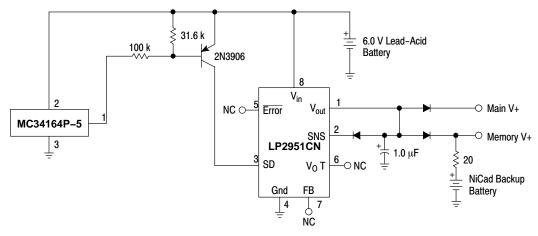


Figure 28. Low Battery Disconnect

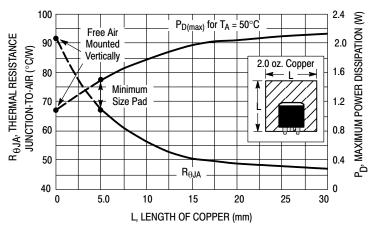


Figure 29. DPAK Thermal Resistance and Maximum Power Dissipation versus PCB Copper Length

ORDERING INFORMATION (LP2950)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping [†]
LP2950CZ-3.0G	3.0	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-3.0RAG	3.0	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950ACZ-3.0G	3.0	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-3.0RAG	3.0	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-3.3G	3.3	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-3.3RAG	3.3	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950ACZ-3.3G	3.3	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-3.3RAG	3.3	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-5.0G	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-5.0RAG	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-5.0RPG	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Ammo Pack
LP2950ACZ-5.0G	5.0	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-5.0RAG	5.0	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CDT-3.0G	3.0	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-3.0RKG	3.0	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-3.0G	3.0	0.5	DPAK (Pb-Free)	75 Units / Rail
LP2950ACDT-3RKG	3.0	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950CDT-3.3G	3.3	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-3.3RKG	3.3	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-3.3RG	3.3	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950CDT-5.0G	5.0	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-5.0RKG	5.0	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-5.0G	5.0	0.5	DPAK (Pb-Free)	75 Units / Rail
LP2950ACDT-5RKG	5.0	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ORDERING INFORMATION (LP2951)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping [†]
LP2951CD-3.0G	3.0	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CD-3.0R2G	3.0	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACD-3.0G	3.0	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACD-3.0R2G	3.0	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CD-3.3G	3.3	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CD-3.3R2G	3.3	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACD-3.3G	3.3	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACD-3.3R2G	3.3	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CDG	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CDR2G	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACDG	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACDR2G	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CDM-3.0R2G	3.0	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDM-3.0RG	3.0	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951CDM-3.3R2G	3.3	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDM-3.3RG	3.3	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951CDMR2G	5.0 or Adj.	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDMR2G	5.0 or Adj.	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACN-3.0G	3.0	0.5	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951CN-3.3G	3.3	1.0	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951ACN-3.3G	3.3	0.5	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951CNG	5.0 or Adj.	1.0	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951ACNG	5.0 or Adj.	0.5	PDIP-8 (Pb-Free)	50 Units / Rail

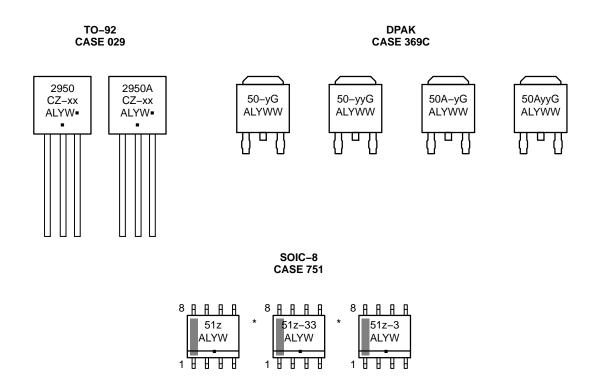
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

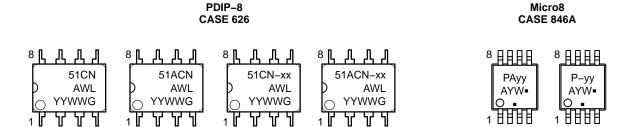
ORDERING INFORMATION (NCV2951)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping [†]
NCV2951ACD3.3R2G*	3.3	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
NCV2951ACDR2G*	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
NCV2951CDR2G*	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

MARKING DIAGRAMS





xx = 3.0, 3.3, or 5.0 y = 3 or 5 yy = 30, 33, or 50 z = A or C

A = Assembly Location WL, L = Wafer Lot

YY, Y = Year
WW, W = Work Week
G = Pb−Free Package
■ Pb−Free Package

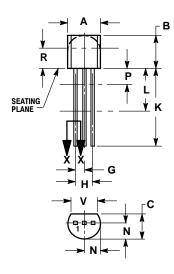
(Note: Microdot may be in either location)

^{*}This marking diagram also applies to NCV2951.

PACKAGE DIMENSIONS

TO-226AA/TO-92 **Z SUFFIX** CASE 29-11

ISSUE AM

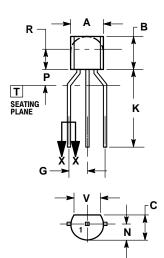


STRAIGHT LEAD **BULK PACK**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES MILLIMETER				
DIM	MIN	MAX	MIN	MAX	
Α	0.175	0.205	4.45	5.20	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.045	0.055	1.15	1.39	
Н	0.095	0.105	2.42	2.66	
J	0.015	0.020	0.39	0.50	
K	0.500		12.70		
L	0.250		6.35		
N	0.080	0.105	2.04	2.66	
P		0.100		2.54	
R	0.115		2.93		
٧	0.135		3.43		



BENT LEAD TAPE & REEL AMMO PACK



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

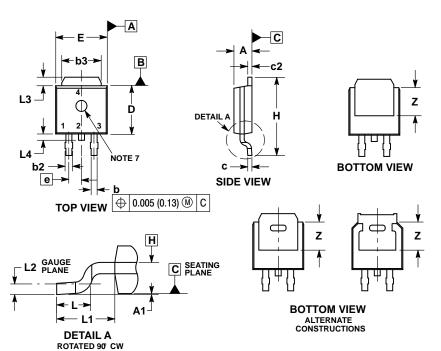
- CONTOUR OF PACKAGE BEYOND
 DIMENSION R IS UNCONTROLLED.
 LEAD DIMENSION IS UNCONTROLLED IN P
 AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS				
DIM	MIN	MAX			
Α	4.45	5.20			
В	4.32	5.33			
С	3.18	4.19			
D	0.40	0.54			
G	2.40	2.80			
J	0.39	0.50			
K	12.70				
N	2.04	2.66			
Р	1.50	4.00			
R	2.93				
v	3 //3				

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: INCHES.

 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

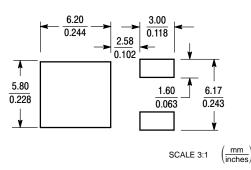
 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29	BSC
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

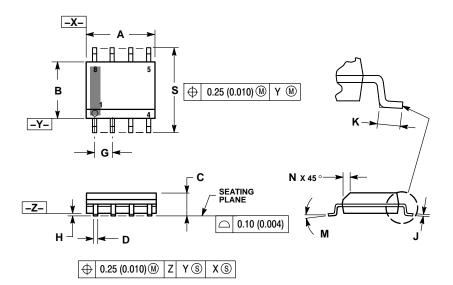
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**



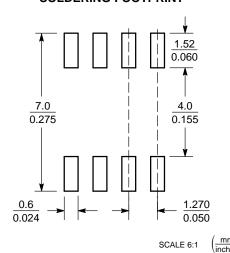
NOTES:

- IES:
 DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.
 751-01 THRU 751-06 ARE OBSOLETE. NEW
 STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BS	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

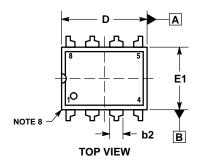


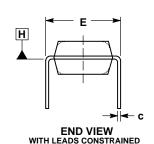
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

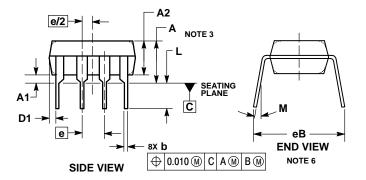
PDIP-8 CASE 626-05 ISSUE P

SCALE 1:1





NOTE 5



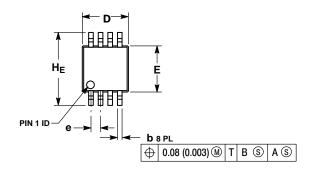
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.

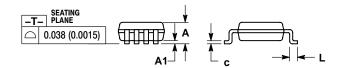
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCHES.
 DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
 DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
 DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM DI ANDE IN WITH INCHES CONSTRAINED DEDBENDICUL AD DIAMED.
- PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
- DIMENSION &B IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
 ACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE
- CORNERS).

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α		0.210		5.33
A1	0.015		0.38	
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060	TYP	1.52	TYP
С	0.008	0.014	0.20	0.36
D	0.355	0.400	9.02	10.16
D1	0.005		0.13	
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
е	0.100	BSC	2.54	BSC
eВ		0.430		10.92
L	0.115	0.150	2.92	3.81
M		10°		10°

PACKAGE DIMENSIONS

Micro8™ CASE 846A-02 **ISSUE J**



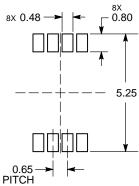


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10		1	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
С	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
е	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
HE	4.75	4.90	5.05	0.187	0.193	0.199

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

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